



PATENT ABSTRACTS OF JAPAN

(11) Publication number: **11346007 A**(43) Date of publication of application: **14 . 12 . 99**(51) Int. Cl. **H01L 33/00**(21) Application number: **10151000**(22) Date of filing: **01 . 06 . 98**(71) Applicant: **MATSUSHITA ELECTRON CORP**(72) Inventor:
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UCHI YOSHIBUMI****(54) SEMICONDUCTOR LIGHT EMITTING DEVICE
AND ITS MANUFACTURING METHOD****(57) Abstract:**

PROBLEM TO BE SOLVED: To provide a semiconductor light emitting device capable of compounding an Si diode and a light emitting element for protecting static electricity to be mounted on a lead frame and wirebonded without short circuiting at all.

SOLUTION: An Si diode 4 and an auxiliary element 5 for protecting static electricity are mounted on a mounting surface of a lead frame or substrate, etc., turning respective main surfaces upward as well as a flipchip type light emitting element 1 on the diode 4 and the auxiliary element 5 turning respective main surfaces downward. Next, the pn junction of the light emitting element 1 connected to the Si diode 4 by microbumps 2a, 3a while the n side electrode 2 of the light emitting element 1 is connected to a conductive pad 5b on the auxiliary element 5 by an adhesive 7 furthermore to be wirebonded to the conductive pad 5b exposed from the light emitting element 1.

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